

MOSFETs Silicon N-Channel MOS (U-MOSVII)

TPCC8076

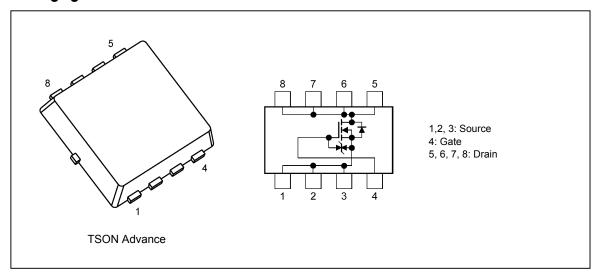
1. Applications

- · Lithium-Ion Secondary Batteries
- Notebook PCs
- · Mobile Equipments

2. Features

- (1) Small footprint due to a small and thin package
- (2) Low drain-source on-resistance: $R_{DS(ON)} = 3.7 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (3) Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 33 \text{ V)}$
- (4) Enhancement mode: V_{th} = 1.3 to 2.3 V (V_{DS} = 10 V, I_{D} = 0.3 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristics				Rating	Unit
Drain-source voltage			V _{DSS}	33	V
Gate-source voltage			V _{GSS}	±20	
Drain current (DC)		(Note 1)	I _D	27	Α
Drain current (pulsed)		(Note 1)	I _{DP}	81	
Power dissipation	(T _c = 25 °C)		P _D	39	W
Power dissipation	(t = 10 s)	(Note 2)	P _D	1.9	
Power dissipation	(t = 10 s)	(Note 3)	P _D	0.7	W
Single-pulse avalanche energy		(Note 4)	E _{AS}	82	mJ
Avalanche current			I _{AR}	27	Α
Channel temperature			T _{ch}	150	°C
Storage temperature			T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

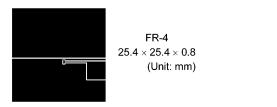
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



5. Thermal Characteristics

Characteristics				Max	Unit
Channel-to-case thermal resistance	$(T_c = 25 ^{\circ}C)$		R _{th(ch-c)}	3.2	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R _{th(ch-a)}	65.7	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R _{th(ch-a)}	178	°C/W

- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1
- Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2
- Note 4: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 0.1 mH, R_G = 1 Ω , I_{AR} = 27 A



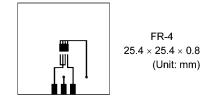


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



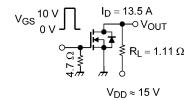
6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μА
Drain cut-off current	I _{DSS}	V _{DS} = 33 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	33	_	_	V
	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	18	_	_	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.3 mA	1.3	_	2.3	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 4.5 V, I _D = 13.5 A	_	4.9	6.2	mΩ
		V _{GS} = 10 V, I _D = 13.5 A	_	3.7	4.6	

6.2. Dynamic Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	2500	_	pF
Reverse transfer capacitance	C _{rss}		_	120	_	
Output capacitance	C _{oss}		_	430	_	
Switching time (rise time)	t _r	See Figure 6.2.1.	_	2.9	_	ns
Switching time (turn-on time)	t _{on}		_	10	_	
Switching time (fall time)	t _f		_	9.5	_	
Switching time (turn-off time)	t _{off}		_	48	_	



Duty \leq 1%, $t_{W}=$ 10 μs

Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 27 \text{ A}$	_	34	_	nC
Gate-source charge 1	Q _{gs1}		_	7.4	_	
Gate-drain charge	Q_{gd}		_	4	_	

6.4. Source-Drain Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Note	: 5) I _{DRP}	_	_	_	81	Α
Diode forward voltage	V_{DSF}	I _{DR} = 27 A, V _{GS} = 0 V	_	_	-1.2	V

Note 5: Ensure that the channel temperature does not exceed 150°C.



7. Marking

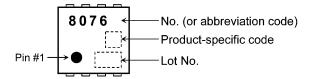


Fig. 7.1 Marking



8. Characteristics Curves (Note)

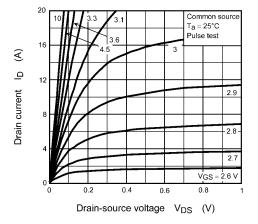


Fig. 8.1 I_D - V_{DS}

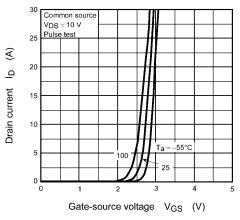


Fig. 8.3 I_D - V_{GS}

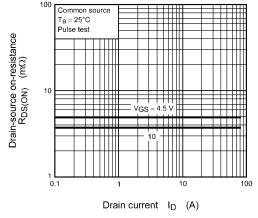


Fig. 8.5 R_{DS(ON)} - I_D

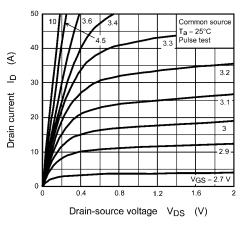


Fig. 8.2 I_D - V_{DS}

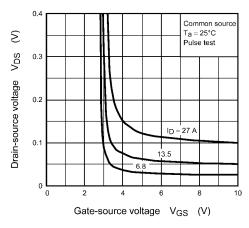


Fig. 8.4 V_{DS} - V_{GS}

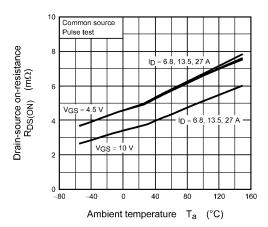


Fig. 8.6 $R_{DS(ON)}$ - T_a

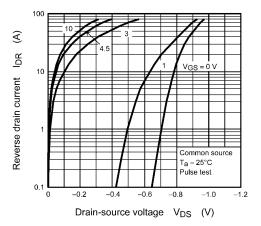


Fig. 8.7 IDR - VDS

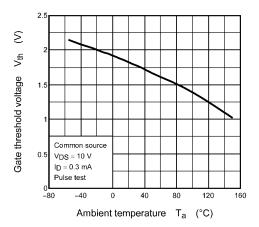


Fig. 8.9 V_{th} - T_a

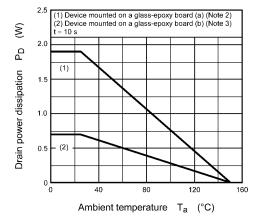


Fig. 8.11 P_D - T_a (Guaranteed Maximum)

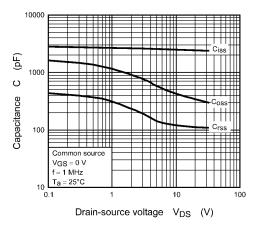


Fig. 8.8 Capacitance - V_{DS}

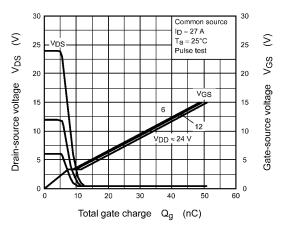


Fig. 8.10 Dynamic Input/Output Characteristics

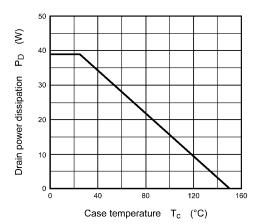


Fig. 8.12 P_D - T_c (Guaranteed Maximum)

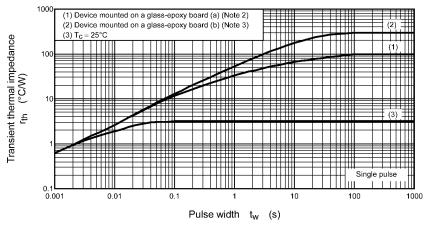


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

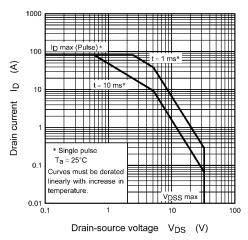
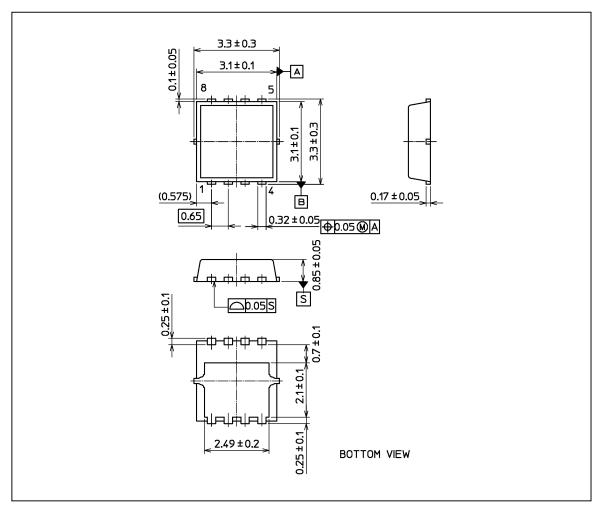


Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.02 g (typ.)

Package Name(s)	
TOSHIBA: 2-3X1S	
Nickname: TSON Advance	



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